

LZP-Series

Highest Lumen Density

Cool White Emitter

LZP-00CW00



Key Features

- Highest luminous flux / area single LED emitter
 - 5000lm Cool White
 - 40mm² light emitting area
- Up to 90 Watt power dissipation on compact 12.0mm x 12.0mm footprint
- Industry lowest thermal resistance per package size (0.6°C/W)
- Industry leading lumen maintenance
- Color Point Stability 7x improvement over Energy Star requirements
- Surface mount ceramic package with integrated glass lens
- JEDEC Level 1 for Moisture Sensitivity Level
- Lead (Pb) free and RoHS compliant
- Reflow solderable (up to 6 cycles)
- Copper core MCPCB option with emitter thermal slug directly soldered to the copper core
- Full suite of TIR secondary optics family available

Typical Applications

- High Bay and Low Bay
- General lighting
- Stage and Studio lighting
- Architectural lighting
- Street lighting

Description

The LZP-00CW00 Cool White LED emitter can dissipate up to 90W of power in an extremely small package. With a small 12.0mm x 12.0mm footprint, this package provides unmatched luminous flux density. LED Engin's patent-pending thermally insulated phosphor layer provides spatial color uniformity across the radiation pattern and a consistent CCT, CRI over time and temperature. The high quality materials used in the package are chosen to optimize light output and minimize stresses which results in superior reliability and lumen maintenance. The robust product design thrives in outdoor applications with high ambient temperatures and high humidity.

Part number options

Base part number

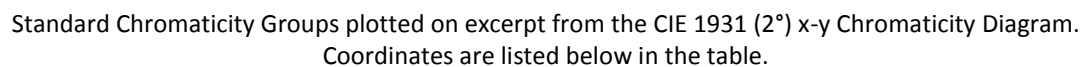
Part number	Description
LZP-00CW00-xxxx	LZP Cool White emitter
LZP-D0CW00-xxxx	LZP Cool White emitter on 5 channel 4x6+1 Star MCPCB
LZP-G0CWT1-xxxx	LZP Cool White emitter on 2 channel 2x12+1 Connectorized MCPCB
LZP-H0CWT1-xxxx	LZP Cool White emitter on 2 channel 4x6+1 Connectorized MCPCB

Bin kit option codes

CW, Cool White (5000K – 6500K)			
Kit number suffix	Min flux Bin	Chromaticity bins	Description
0000	G2	1U, 1A, 1B, 1V, 1Y, 1D, 1C, 1X, 2U, 2A, 2B, 2V, 2Y, 2D, 2C, 2X, 3U, 3A, 3B, 3V, 3Y, 3D, 3C, 3X	full distribution flux; full distribution CCT
H000	H2	1U, 1A, 1B, 1V, 1Y, 1D, 1C, 1X, 2U, 2A, 2B, 2V, 2Y, 2D, 2C, 2X, 3U, 3A, 3B, 3V, 3Y, 3D, 3C, 3X	H2= minimum flux bin; full distribution CCT
0050	G2	2Y, 2D, 2C, 2X, 3U, 3A, 3B, 3V, 3Y, 3D, 3C, 3X	full distribution flux; 5000K bin
H050	H2	2Y, 2D, 2C, 2X, 3U, 3A, 3B, 3V, 3Y, 3D, 3C, 3X	H2=minimum flux bin; 5000K bin
0055	G2	2U, 2Y, 3U, 2A, 2D, 3A, 2B, 2C, 3B, 2V, 2X, 3V	full distribution flux; 5500K bin
H055	H2	2U, 2Y, 3U, 2A, 2D, 3A, 2B, 2C, 3B, 2V, 2X, 3V	H2=minimum flux bin; 5500K bin
0056	G2	1Y, 1D, 1C, 1X, 2U, 2A, 2B, 2V, 2Y, 2D, 2C, 2X	full distribution flux; 5600K bin
H056	H2	1Y, 1D, 1C, 1X, 2U, 2A, 2B, 2V, 2Y, 2D, 2C, 2X	H2=minimum flux bin; 5600K bin
0065	G2	1U, 1A, 1B, 1V, 1Y, 1D, 1C, 1X, 2U, 2A, 2B, 2V	full distribution flux; 6500K bin
H065	H2	1U, 1A, 1B, 1V, 1Y, 1D, 1C, 1X, 2U, 2A, 2B, 2V	H2=minimum flux bin; 6500K bin

Notes:

1. Default bin kit option is -0000



Cool White Bin Coordinates

Bin code	CIE _x	CIE _y	Bin code	CIE _x	CIE _y	Bin code	CIE _x	CIE _y	Bin code	CIE _x	CIE _y
1U	0.3068	0.3113	1A	0.3048	0.3207	1B	0.3028	0.3304	1V	0.3005	0.3415
	0.3144	0.3186		0.313	0.329		0.3115	0.3391		0.3099	0.3509
	0.3161	0.3059		0.3144	0.3186		0.313	0.329		0.3115	0.3391
	0.3093	0.2993		0.3068	0.3113		0.3048	0.3207		0.3028	0.3304
1Y	0.3068	0.3113	1D	0.3048	0.3207	1C	0.3028	0.3304	1X	0.3005	0.3415
	0.3144	0.3186		0.313	0.329		0.3115	0.3391		0.3099	0.3509
	0.3221	0.3261		0.3213	0.3373		0.3205	0.3481		0.3196	0.3602
	0.3231	0.312		0.3221	0.3261		0.3213	0.3373		0.3205	0.3481
2U	0.3161	0.3059	2A	0.3144	0.3186	2B	0.313	0.329	2V	0.3115	0.3391
	0.3144	0.3186		0.313	0.329		0.3115	0.3391		0.3099	0.3509
	0.3222	0.3243		0.3215	0.335		0.3207	0.3462		0.3196	0.3602
	0.329	0.33		0.329	0.3417		0.329	0.3538		0.329	0.369
2Y	0.329	0.318	2D	0.329	0.33	2C	0.329	0.3417	2X	0.329	0.3538
	0.3231	0.312		0.3222	0.3243		0.3215	0.335		0.3207	0.3462
	0.3222	0.3243		0.3215	0.335		0.3207	0.3462		0.3196	0.3602
	0.329	0.33		0.329	0.3417		0.329	0.3538		0.329	0.369
3U	0.3366	0.3369	3A	0.3371	0.349	3B	0.3376	0.3616	3V	0.3381	0.3762
	0.344	0.3428		0.3451	0.3554		0.3463	0.3687		0.348	0.384
	0.3429	0.3299		0.344	0.3427		0.3451	0.3554		0.3463	0.3687
	0.3361	0.3245		0.3366	0.3369		0.3371	0.349		0.3376	0.3616
3Y	0.3366	0.3369	3D	0.3371	0.349	3C	0.3376	0.3616	3X	0.3381	0.3762
	0.344	0.3428		0.3451	0.3554		0.3463	0.3687		0.348	0.384
	0.3515	0.3487		0.3533	0.362		0.3551	0.376		0.3571	0.3907
	0.3495	0.3339		0.3515	0.3487		0.3533	0.362		0.3551	0.376
	0.3429	0.3299		0.344	0.3427		0.3451	0.3554		0.3463	0.3687
	0.344	0.3428		0.3451	0.3554		0.3463	0.3687		0.348	0.384

Luminous Flux Bins

Table 1:

Bin Code	Minimum Luminous Flux (Φ_v) @ $I_F = 700\text{mA}$ /Channel ^[1,2] (lm)	Maximum Luminous Flux (Φ_v) @ $I_F = 700\text{mA}$ /Channel ^[1,2] (lm)
G2	3,200	3,500
H2	3,500	3,800
J2	3,800	4,200
K2	4,200	4,600

Notes:

1. Luminous flux performance guaranteed within published operating conditions. LED Engin maintains a tolerance of $\pm 10\%$ on flux measurements.
2. Luminous Flux typical value is for all 24 LED dies operating at rated current. The LED is configured with 4 Channels of 6 dies in series.

Forward Voltage Bin

Table 2:

Bin Code	Minimum Forward Voltage (V_F) @ $I_F = 700\text{mA}$ /Channel ^[1] (V)	Maximum Forward Voltage (V_F) @ $I_F = 700\text{mA}$ /Channel ^[1] (V)
0	19.20 ^[2,3]	23.52 ^[2,3]

Notes:

1. LED Engin maintains a tolerance of $\pm 0.24\text{V}$ for forward voltage measurements.
2. All 4 white Channels have matched V_F for parallel operation
3. Forward Voltage is binned with 6 LED dies connected in series. The LED is configured with 4 Channels of 6 dies in series each.

Absolute Maximum Ratings

Table 3:

Parameter	Symbol	Value	Unit
DC Forward Current at $T_{jmax}=135^{\circ}\text{C}^{[1]}$	I_F	1200	mA
DC Forward Current at $T_{jmax}=150^{\circ}\text{C}^{[1]}$	I_F	1000	mA
Peak Pulsed Forward Current ^[2]	I_{FP}	1500 /Channel	mA
Reverse Voltage	V_R	See Note 3	V
Storage Temperature	T_{stg}	-40 ~ +150	$^{\circ}\text{C}$
Junction Temperature	T_J	150	$^{\circ}\text{C}$
Soldering Temperature ^[4]	T_{sol}	260	$^{\circ}\text{C}$
Allowable Reflow Cycles		6	
ESD Sensitivity ^[5]		> 8,000 V HBM Class 3B JESD22-A114-D	

Notes:

- Maximum DC forward current (per die) is determined by the overall thermal resistance and ambient temperature. Follow the curves in Figure 10 for current de-rating.
- Pulse forward current conditions: Pulse Width $\leq 10\text{msec}$ and Duty cycle $\leq 10\%$.
- LEDs are not designed to be reverse biased.
- Solder conditions per JEDEC 020D. See Reflow Soldering Profile Figure 5.
- LED Engin recommends taking reasonable precautions towards possible ESD damages and handling the LZP-00CW00 in an electrostatic protected area (EPA). An EPA may be adequately protected by ESD controls as outlined in ANSI/ESD S6.1.

Optical Characteristics @ $T_c = 25^{\circ}\text{C}$

Table 4:

Parameter	Symbol	Typical	Unit
Luminous Flux (@ $I_F = 700\text{mA}$) ^[1]	Φ_V	3900	lm
Luminous Flux (@ $I_F = 1000\text{mA}$) ^[1]	Φ_V	5000	lm
Luminous Efficacy (@ $I_F = 350\text{mA}$)		86	lm/W
Correlated Color Temperature	CCT	5500	K
Color Rendering Index (CRI)	R_a	75	
Viewing Angle ^[2]	$2\Theta_{1/2}$	110	Degrees

Notes:

- Luminous flux typical value is for all 24 LED dies operating at rated current.
- Viewing Angle is the off-axis angle from emitter centerline where the luminous intensity is $\frac{1}{2}$ of the peak value.

Electrical Characteristics @ $T_c = 25^{\circ}\text{C}$

Table 5:

Parameter	Symbol	Typical	Unit
Forward Voltage (@ $I_F = 700\text{mA}$) ^[1]	V_F	21.0 /Channel	V
Forward Voltage (@ $I_F = 1000\text{mA}$) ^[1]	V_F	21.9 /Channel	V
Temperature Coefficient of Forward Voltage ^[1]	$\Delta V_F / \Delta T_J$	-16.8	mV/ $^{\circ}\text{C}$
Thermal Resistance (Junction to Case)	$R\Theta_{J-C}$	0.6	$^{\circ}\text{C}/\text{W}$

Notes:

- Forward Voltage is measured for a single string of 6 dies connected in series. The LED is configured with 4 Channels of 6 dies in series each.

IPC/JEDEC Moisture Sensitivity Level

Table 6 - IPC/JEDEC J-STD-20D.1 MSL Classification:

Level	Floor Life		Standard		Soak Requirements	
	Time	Conditions	Time (hrs)	Conditions	Accelerated	Time (hrs)
1	unlimited	$\leq 30^{\circ}\text{C}/$ 85% RH	168 +5/-0	$85^{\circ}\text{C}/$ 85% RH	n/a	n/a

Notes:

- The standard soak time includes a default value of 24 hours for semiconductor manufacturer's exposure time (MET) between bake and bag and includes the maximum time allowed out of the bag at the distributor's facility.

Average Lumen Maintenance Projections

Lumen maintenance generally describes the ability of a lamp to retain its output over time. The useful lifetime for solid state lighting devices (Power LEDs) is also defined as Lumen Maintenance, with the percentage of the original light output remaining at a defined time period. L70 defines the amount of operating hours at which the light output has reached 70% of its original output.

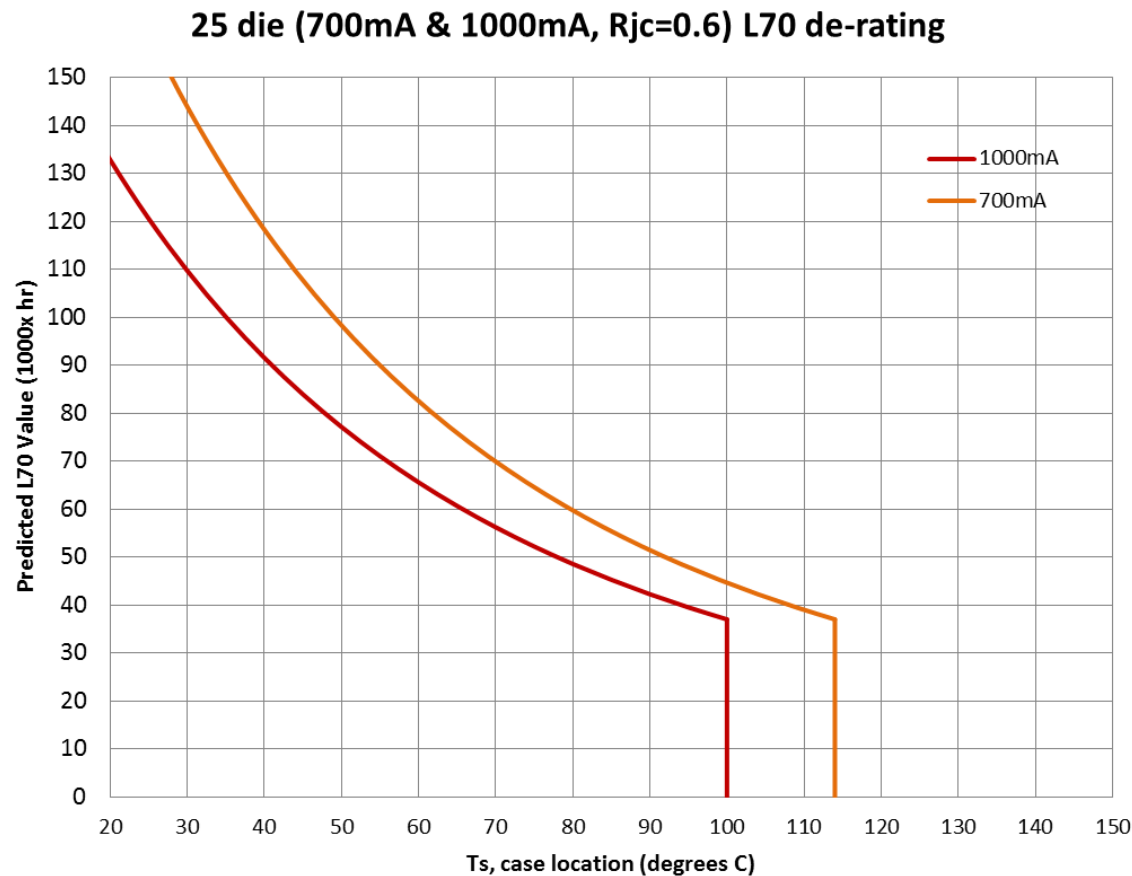
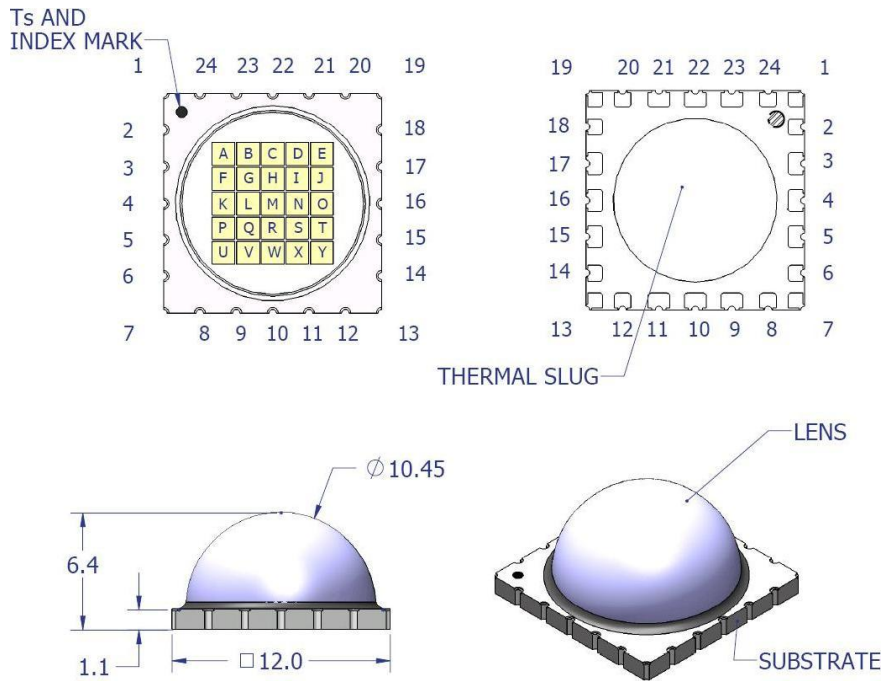


Figure 1: De-rating curve for operation of all dies at 700mA

Notes:

- Ts is a thermal reference point on the emitter case

Mechanical Dimensions (mm)



Notes:

1. Unless otherwise noted, the tolerance = ± 0.20 mm.
2. Thermal slug is electrically isolated
3. Ts is a thermal reference point

Pin Out				
Ch.	Pad	Die	Color	Function
1	18	E	CW	Anode
		D	CW	na
		C	CW	na
		B	CW	na
		A	CW	na
2	24	F	CW	Cathode
	17	J	CW	Anode
		I	CW	na
		H	CW	na
		G	CW	na
		L	CW	na
3	3	K	CW	Cathode
	15	O	CW	Anode
		N	CW	na
		S	CW	na
		R	CW	na
4	5	P	CW	Cathode
	14	T	CW	Anode
		Y	CW	na
		X	CW	na
		W	CW	na
5	8	V	CW	na
	2	U	CW	Cathode
5	23	M	-	na
		M	-	na

Recommended Solder Pad Layout (mm)

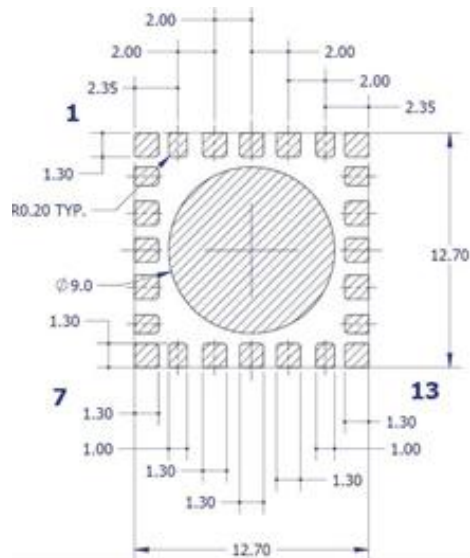


Figure 3: Recommended solder mask opening (hatched area) for anode, cathode, and thermal pad.

Notes:

1. Unless otherwise noted, the tolerance = ± 0.20 mm.
2. LED Engin recommends the use of copper core MCPCB's which allow for the emitter thermal slug to be soldered directly to the copper core (so called pedestal design). Such MCPCB technologies eliminate the high thermal resistance dielectric layer that standard MCPCB technologies use in between the emitter thermal slug and the metal core of the MCPCB, thus lowering the overall system thermal resistance.
3. LED Engin recommends x-ray sample monitoring for solder voids underneath the emitter thermal slug. The total area covered by solder voids should be less than 20% of the total emitter thermal slug area. Excessive solder voids will increase the emitter to MCPCB thermal resistance and may lead to higher failure rates due to thermal over stress.

Reflow Soldering Profile

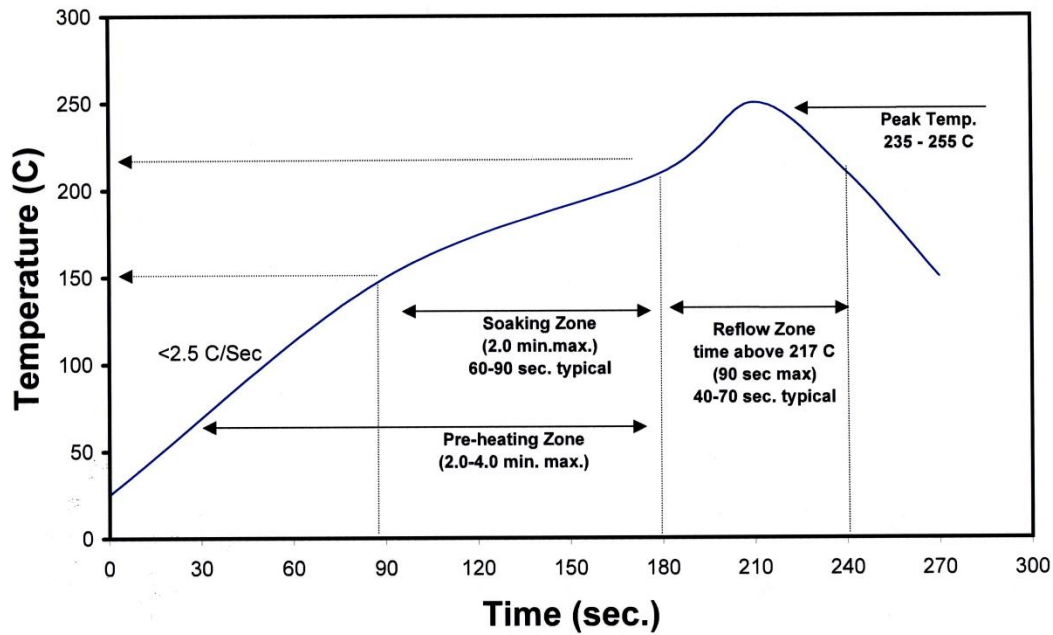


Figure 4: Reflow soldering profile for lead free soldering.

Typical Radiation Pattern

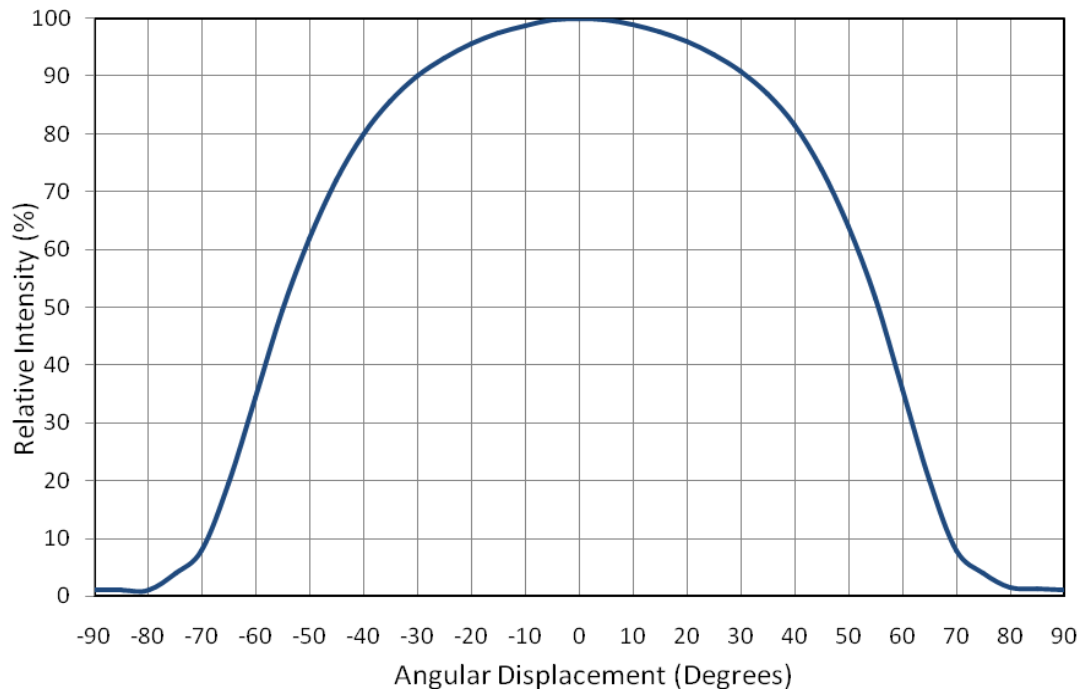


Figure 5: Typical representative spatial radiation pattern.

Typical Relative Spectral Power Distribution

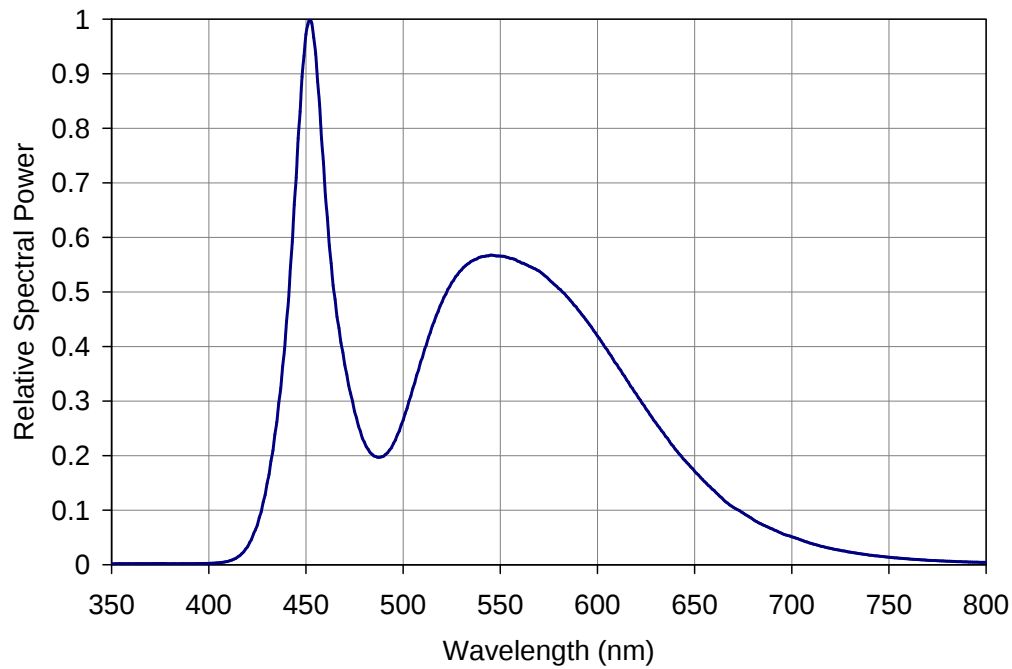


Figure 6: Typical relative spectral power vs. wavelength @ $T_C = 25^\circ\text{C}$.

Typical Relative Light Output

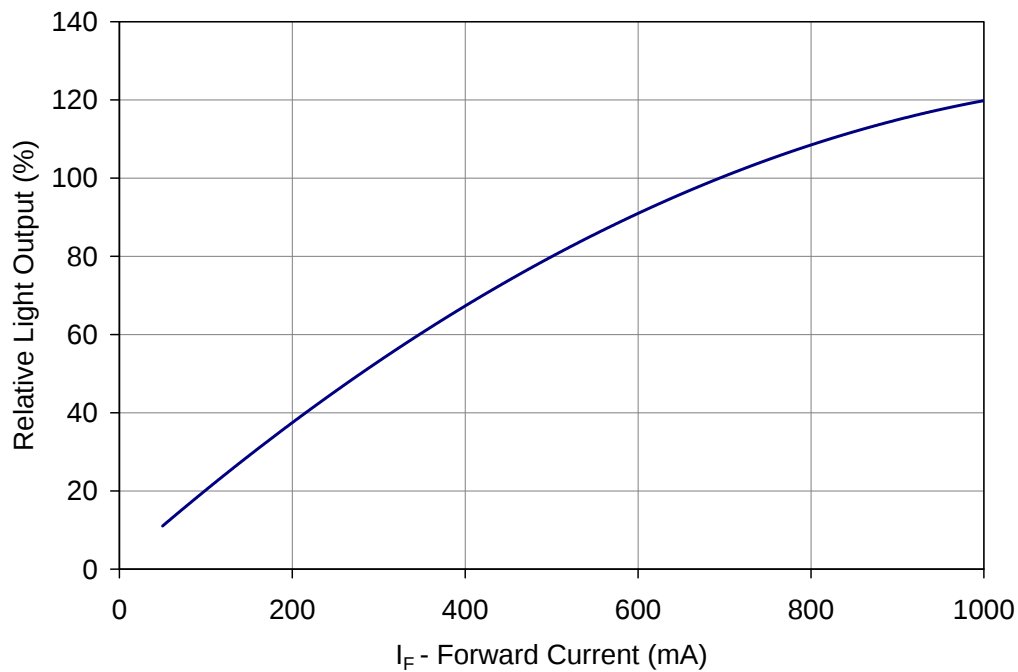


Figure 7: Typical relative light output vs. forward current @ $T_C = 25^\circ\text{C}$.

Notes:

1. Luminous Flux typical value is for all 24 LED dies operating concurrently at rated current pro Channel.

Typical Relative Light Output over Temperature

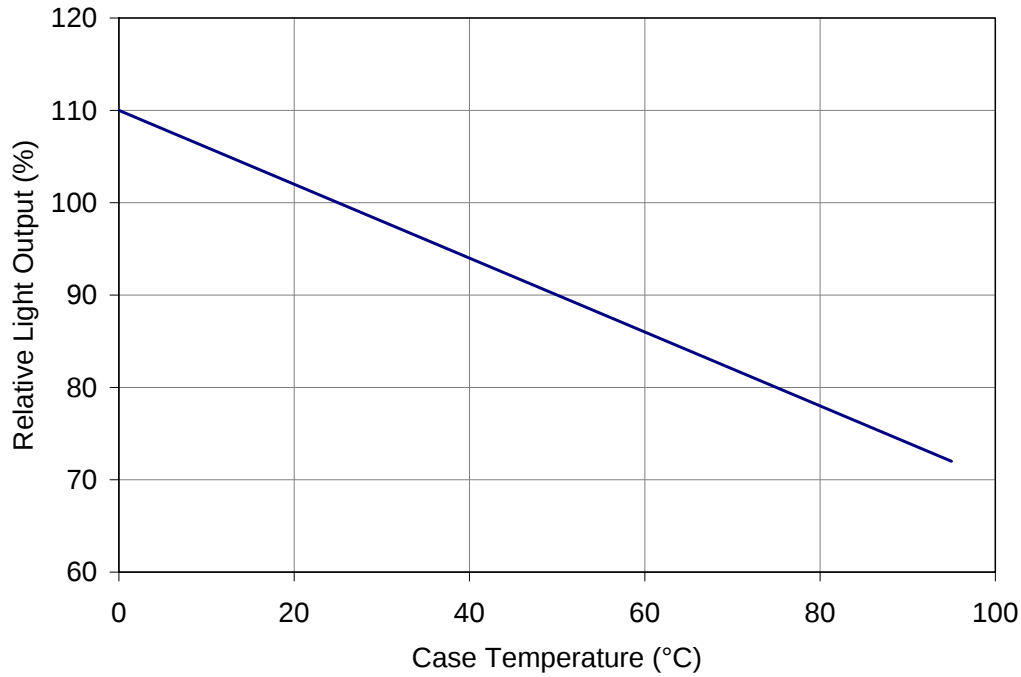


Figure 8: Typical relative light output vs. case temperature.

Notes:

1. Luminous Flux typical value is for all 24 LED dies operating concurrently at rated current pro Channel.

Typical Forward Current Characteristics

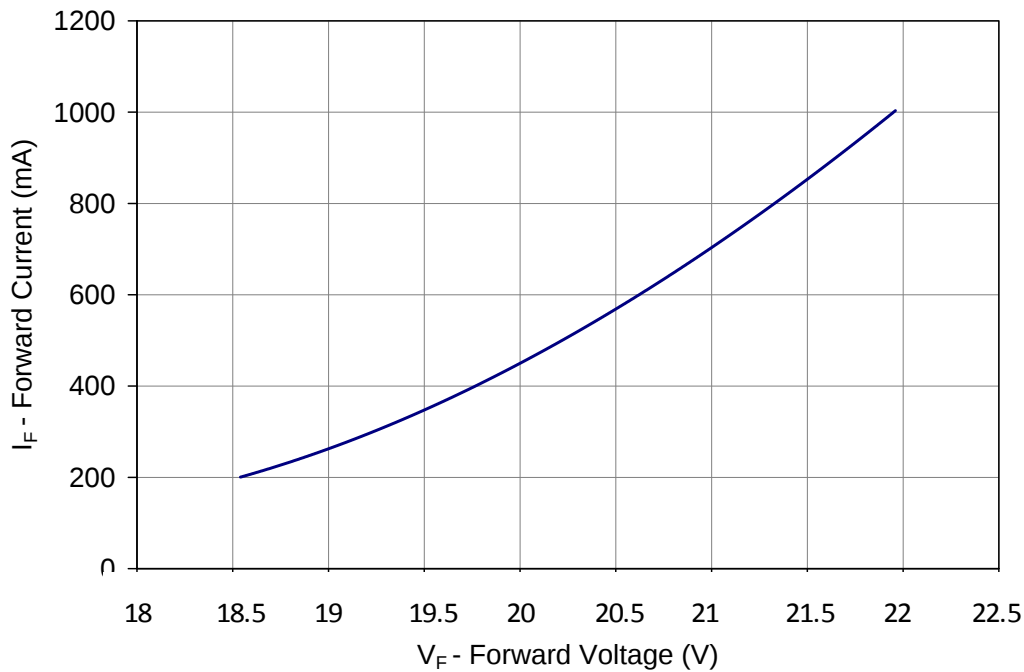


Figure 9: Typical forward current vs. forward voltage @ $T_c = 25^\circ\text{C}$.

Note:

1. Forward Voltage is measured for a single string of 6 dies connected in series. The LED is configured with 4 Channels of 6 dies in series each.

Color over Angle Pattern

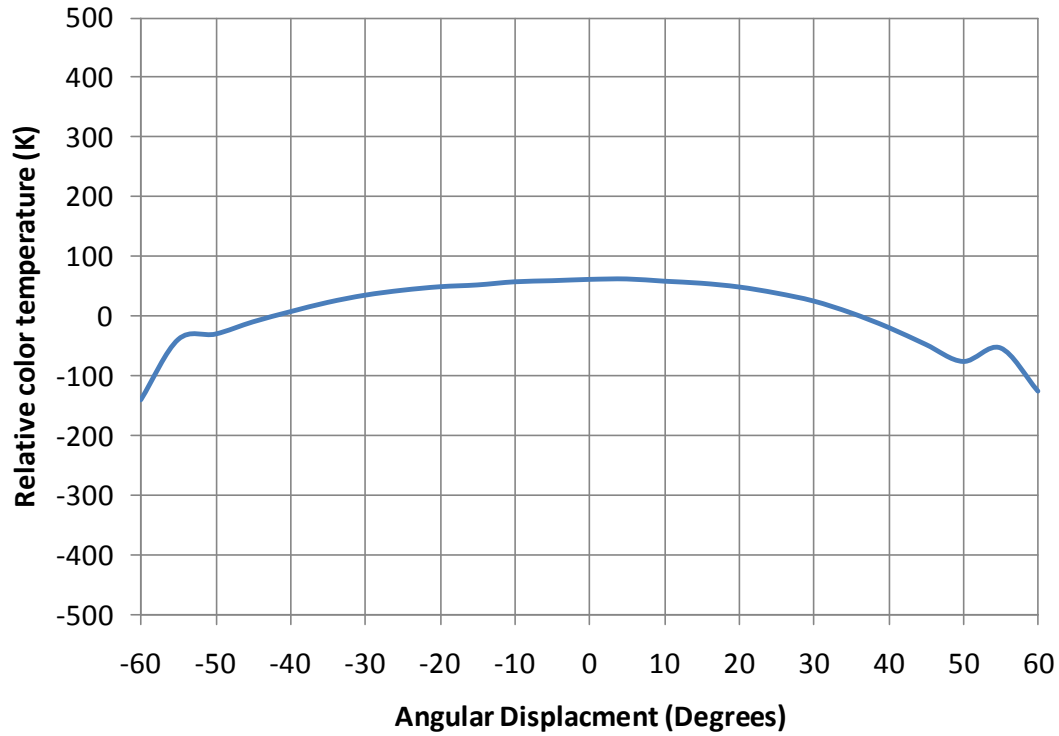


Figure 10: Typical representative color over angle pattern (includes 95% of the luminous flux).

Current De-rating

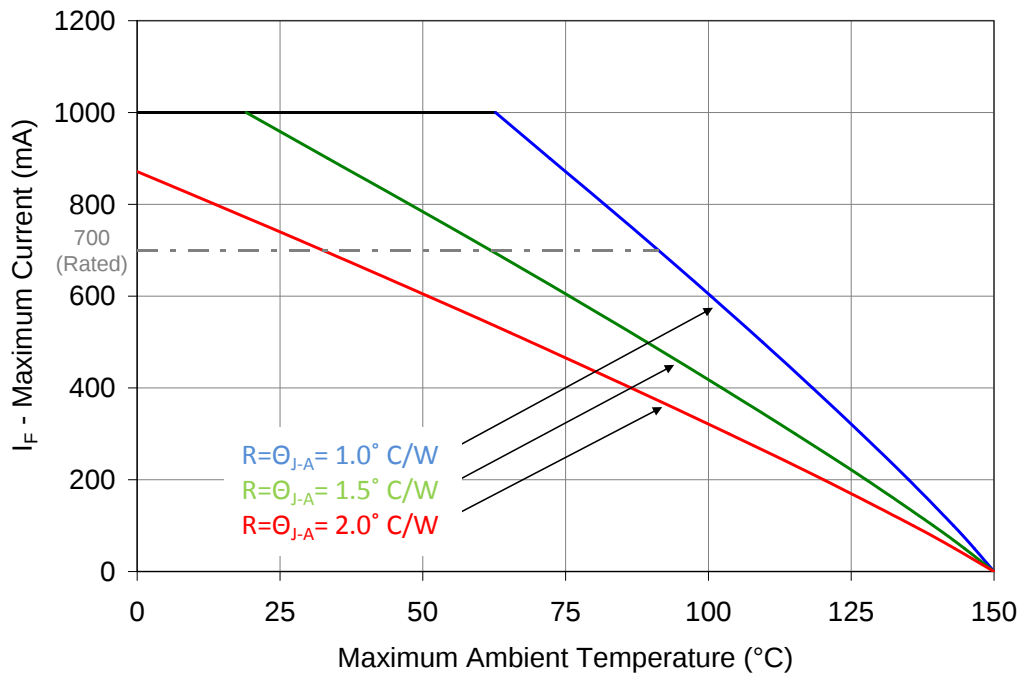


Figure 11: Maximum forward current vs. ambient temperature based on $T_{j(MAX)} = 150^{\circ}\text{C}$.

Notes:

1. Maximum current assumes that all LED dies are operating at rated current.
2. RO_{J-C} [Junction to Case Thermal Resistance] for the LZP-series is typically 0.6°C/W .
3. RO_{J-A} [Junction to Ambient Thermal Resistance] = $RO_{J-C} + RO_{C-A}$ [Case to Ambient Thermal Resistance].

Emitter Tape and Reel Specifications (mm)

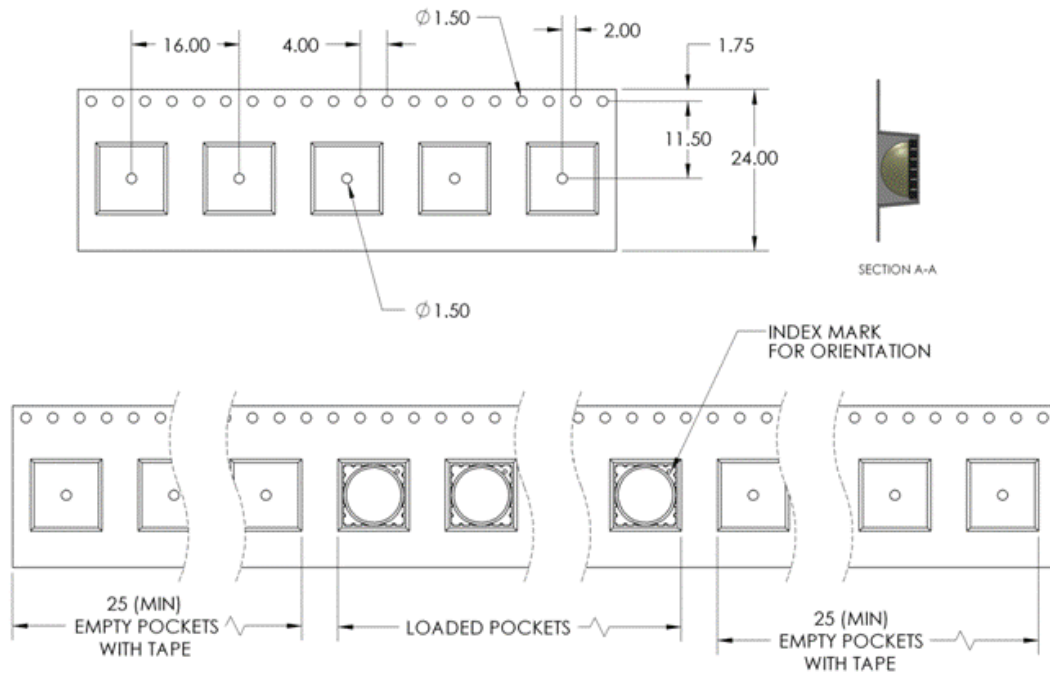


Figure 12: Emitter carrier tape specifications (mm).

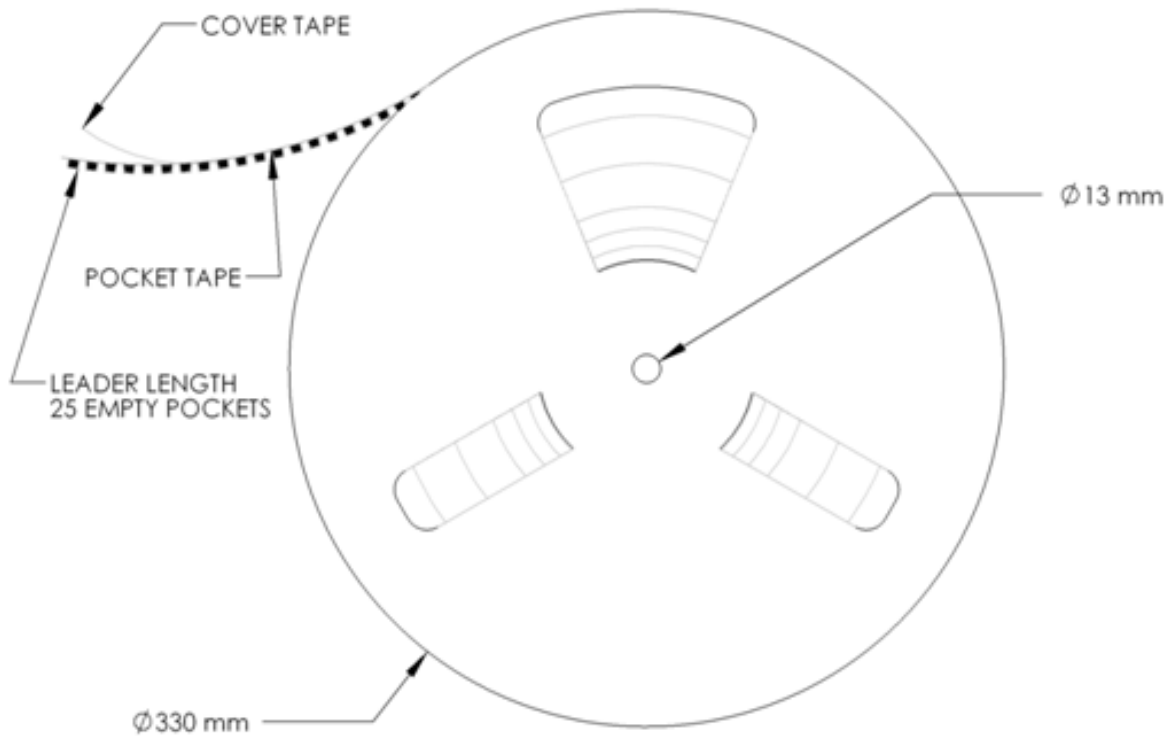


Figure 13: Emitter Reel specifications (mm).

LZP MCPCB Family

Part number	Type of MCPCB	Diameter (mm)	Emitter + MCPCB Thermal Resistance (°C/W)	Typical V _f (V)	Typical I _f (mA)
LZP-Dxxxxx	5-channel (4x6+1 strings)	28.3	0.6 + 0.1 = 0.7	21.0	4 x 700
LZP-GxxxT1	2-channel (2 x 12 + 1 string)	49.5	0.6 + 0.1 = 0.7	42.0	1400
LZP-HxxxT1	2-channel (4 x 6 + 1 string)	49.5	0.6 + 0.1 = 0.7	21.0	2800

Mechanical Mounting of MCPCB

- MCPCB bending should be avoided as it will cause mechanical stress on the emitter, which could lead to substrate cracking and subsequently LED dies cracking.
- To avoid MCPCB bending:
 - Special attention needs to be paid to the flatness of the heat sink surface and the torque on the screws.
 - Care must be taken when securing the board to the heat sink. This can be done by tightening three M3 screws (or #4-40) in steps and not all the way through at once. Using fewer than three screws will increase the likelihood of board bending.
 - It is recommended to always use plastics washers in combinations with the three screws.
 - If non-taped holes are used with self-tapping screws, it is advised to back out the screws slightly after tightening (with controlled torque) and then re-tighten the screws again.

Thermal interface material

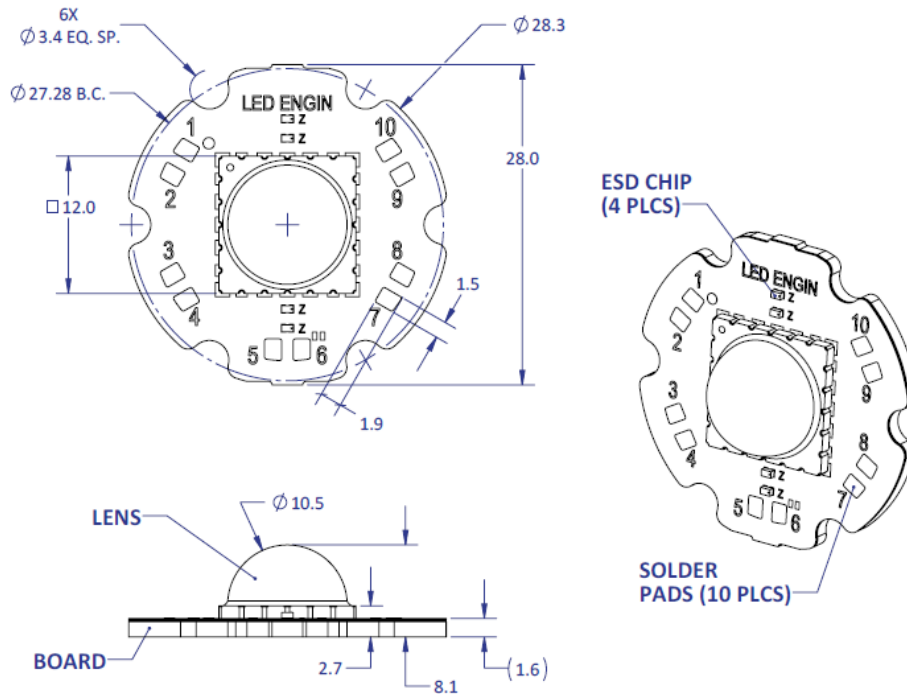
- To properly transfer heat from LED emitter to heat sink, a thermally conductive material is required when mounting the MCPCB on to the heat sink.
- There are several varieties of such material: thermal paste, thermal pads, phase change materials and thermal epoxies. An example of such material is Electrolube EHTC.
- It is critical to verify the material's thermal resistance to be sufficient for the selected emitter and its operating conditions.

Wire soldering

- To ease soldering wire to MCPCB process, it is advised to preheat the MCPCB on a hot plate of 125-150°C. Subsequently, apply the solder and additional heat from the solder iron will initiate a good solder reflow. It is recommended to use a solder iron of more than 60W.
- It is advised to use lead-free, no-clean solder. For example: SN-96.5 AG-3.0 CU 0.5 #58/275 from Kester (pn: 24-7068-7601)

LZP-Dxxxxxx

5-Channel, Standard Star MCPCB (4x6+1) Dimensions (mm)



Notes:

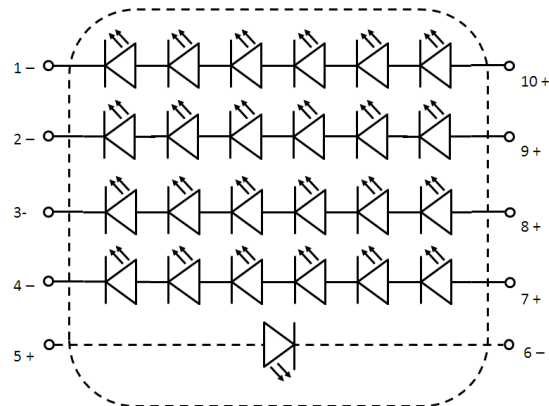
- Unless otherwise noted, the tolerance = ± 0.20 mm.
- Slots in MCPCB are for M3 or #4 mounting screws.
- LED Engin recommends using plastic washers to electrically insulate screws from solder pads and electrical traces.
- LED Engin recommends using thermal interface material when attaching the MCPCB to a heat sink.
- LED Engin uses a copper core MCPCB with pedestal design, allowing direct solder connect between the MCPCB copper core and the emitter thermal slug. The thermal resistance of this copper core MCPCB is: R θ C-B 0.1°C/W

Components used

MCPCB: SuperMCPCB
ESD chips: BZT52C36LP

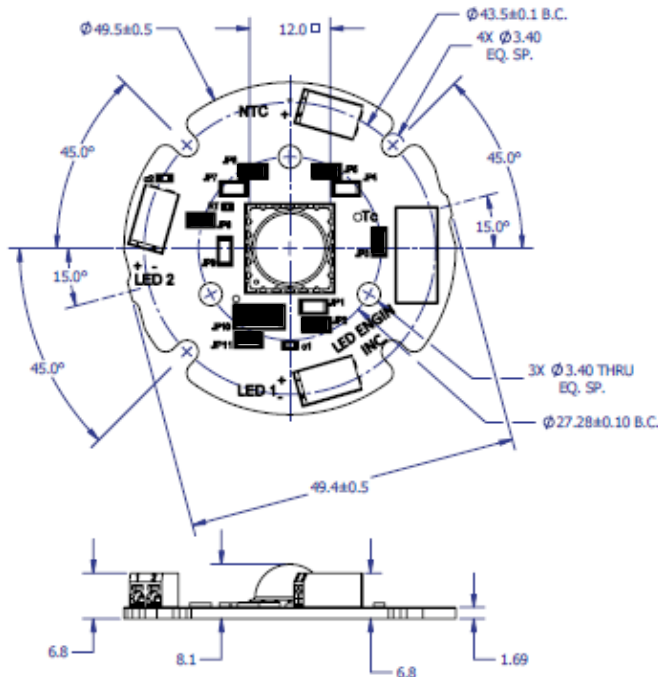
(Bridge Semiconductor, copper core with pedestal design)
(NXP, for 6 LED dies in series)

Pad layout			
Ch.	MCPCB Pad	String/die	Function
1	1	1/EDCBAF	Cathode -
	10		Anode +
2	2	2/JIHGLK	Cathode -
	9		Anode +
3	3	3/ONSRQP	Cathode -
	8		Anode +
4	4	4/TYXWVU	Cathode -
	7		Anode +
5	5	5/M	N/A
	6		N/A



LZP-GxxxT1

2-Channel, Connectorized MCPCB with Thermistor (2x12+1) Dimensions (mm)



Notes:

- Unless otherwise noted, the tolerance = ± 0.2 mm. angle = $\pm 1^\circ$
- Slots in MCPCB are for M3 or #4-40 mounting screws. Maximum torque should not exceed 1N-m (8.9 lbf-in)
- LED Engin recommends plastic washers to electrically insulate screws from solder pads and electrical traces.
- LED Engin recommends using thermally interface material when attaching the MCPCB to a heatsink
- For the connectors it is recommended to use solid wires with gauge size, 18, 20 or 22 AWG. It is recommended to strip the insulation of the wires to a length of 4-5mm. When stranded wires are used it is recommended to twist the strands at the end of the wire and use wire extraction toll to insert the wires.
- LED Engin uses a copper core MCPCB with pedestal design, allowing direct solder connect between the MCPCB copper core and the emitter thermal slug. The thermal resistance of this copper core MCPCB is: $\theta_{JC-B} 0.1^\circ\text{C/W}$

Components used

MCPCB: SuperMCPCB

ESD chips: BZX585-C51

BZX585-C9

Thermistor: NCP15WF104F03RC

Connectors: 00-9276-002-0-21-1-06

(Bridge Semiconductor, copper core with pedestal design)

(NXP, for 12 LED dies in series)

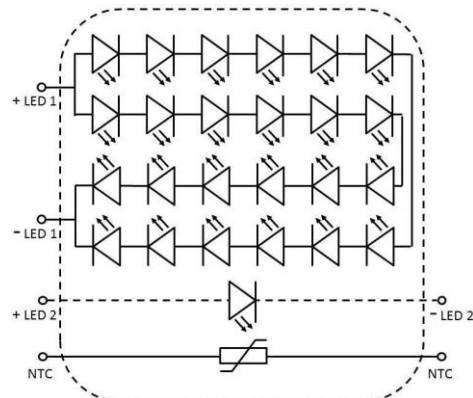
(NXP, for optional center die)

(Murata, 100kOhm for the LZx-xxxxT1, please see

www.murata.com for details on calculating the thermistor temperature)

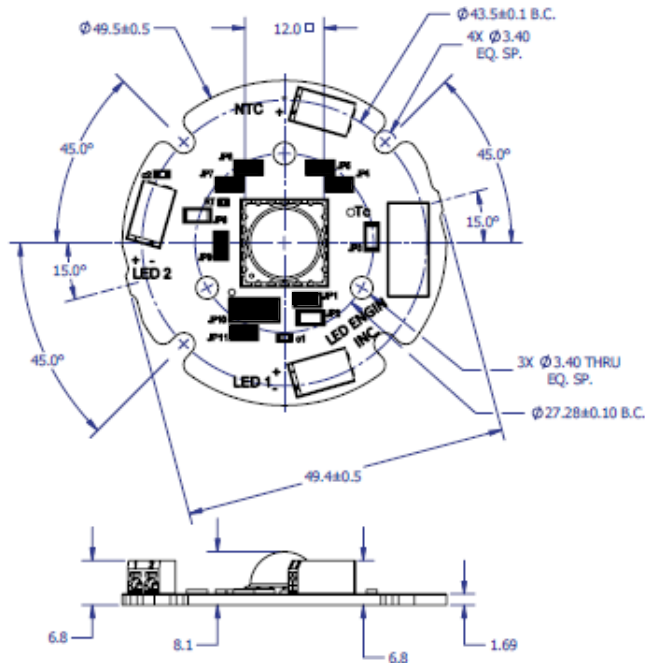
(AVX, poke-home)

Ch.	Pad	Emitter pin	Function
1	LED1+	15, 17	Anode
	LED1-	8, 24	Cathode
2	LED2+	2	Anode
	LED2-	23	Cathode
T	NTC	na	Anode
	NTC	na	Cathode



LZP-HxxxT1

2-Channel, Connectorized MCPCB with Thermistor (4x6+1) Dimensions (mm)



Note for Figure 1:

- Unless otherwise noted, the tolerance = ± 0.2 mm, angle = $\pm 1^\circ$
- Slots in MCPCB are for M3 or #4-40 mounting screws. Maximum torque should not exceed 1N-m (8.9 lbf-in)
- LED Engin recommends plastic washers to electrically insulate screws from solder pads and electrical traces.
- LED Engin recommends using thermally interface material when attaching the MCPCB to a heatsink
- For the connectors it is recommended to use solid wires with gauge size, 18, 20 or 22 AWG. It is recommended to strip the insulation of the wires to a length of 4-5mm. When stranded wires are used it is recommended to twist the strands at the end of the wire and use wire extraction toll to insert the wires.
- LED Engin uses a copper core MCPCB with pedestal design, allowing direct solder connect between the MCPCB copper core and the emitter thermal slug. The thermal resistance of this copper core MCPCB is: R0C-B 0.1°C/W

Components used

MCPCB: SuperMCPCB

ESD chips: BZX585-C30

BZX585-C9

Thermistor: NCP15WF104F03RC

Connectors: 00-9276-002-0-21-1-06

(Bridge Semiconductor, copper core with pedestal design)

(NXP, for 6 LED dies in series)

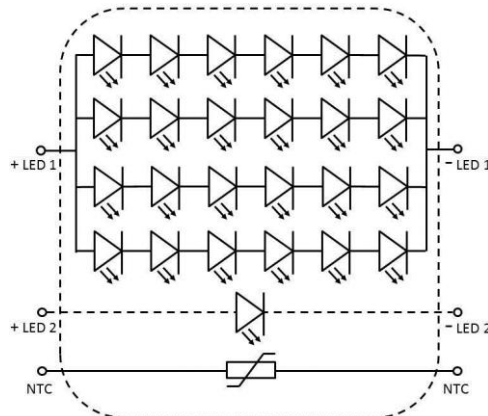
(NXP, for optional center die)

(Murata, 100kOhm for the LZx-xxxxT1, please see

www.murata.com for details on calculating the thermistor temperature)

(AVX, poke-home)

Ch.	Pad	Emitter pin	Function
1	LED1+	14, 15, 17, 18	Anode
	LED1-	8, 5, 3, 24	Cathode
2	LED2+	2	Anode
	LED2-	23	Cathode
T	NTC	na	Anode
	NTC	na	Cathode

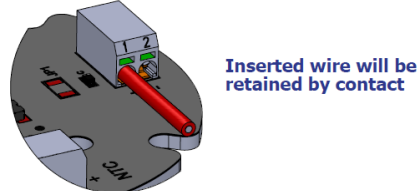
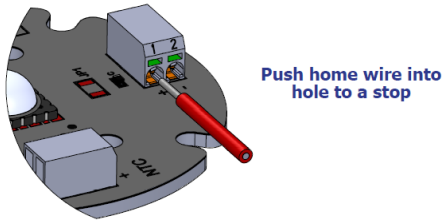


Appendix: Wire Insertion and Extraction Instructions AVX poke-home

For the AVX poke-home it is recommended to use solid wires with gauge size, 18, 20 or 22 AWG, but stranded wire can be used as well. Push the wire in and then give slight tug on the wire to confirm that it is properly engaged.

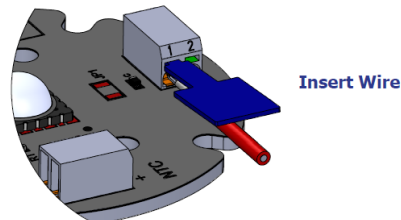
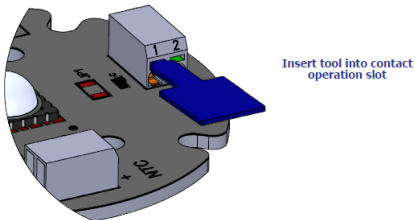
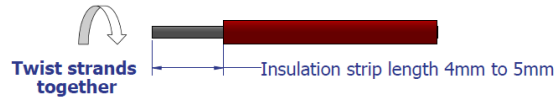
Wire Insertion Solid conductor

- Strip insulation length 4-5mm
- Insert into appropriate hole to a stop
- Inserted wire will be retained by contact



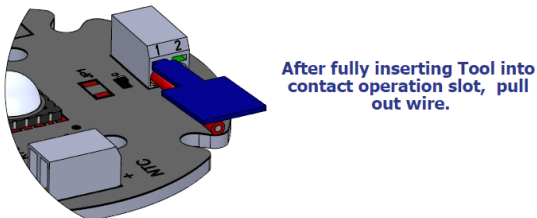
Wire Insertion Stranded wire conductor

- Twist strands together
- Insert tool into contact operation slot
- Insert wire
- Remove tool



Wire extraction

- Insert tool into contact
- Extract wire
- Remove tool



Extraction Tool References:

Thin Blade Wire Extraction Tool: AVX P/N - 0692-7670-0101-000 or
Miniature Precision Screw Driver, 0.047" Tip Width

Company Information

LED Engin, based in California's Silicon Valley, develops, manufactures, and sells advanced LED emitters, optics and light engines to create uncompromised lighting experiences for a wide range of entertainment, architectural, general lighting and specialty applications. LuxiGen™ multi-die emitter and secondary lens combinations reliably deliver industry-leading flux density, upwards of 5000 quality lumens to a target, in a wide spectrum of colors including whites, tunable whites, multi-color and UV LEDs in a unique patented compact ceramic package. Our LuxiTune™ series of tunable white lighting modules leverage our LuxiGen emitters and lenses to deliver quality, control, freedom and high density tunable white light solutions for a broad range of new recessed and downlighting applications. The small size, yet remarkably powerful beam output and superior in-source color mixing, allows for a previously unobtainable freedom of design wherever high-flux density, directional light is required.

LED Engin is committed to providing products that conserve natural resources and reduce greenhouse emissions.

LED Engin reserves the right to make changes to improve performance without notice.

Please contact sales@ledengin.com or (408) 922-7200 for more information.